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(54) **POWER MODULE**

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**ABSTRACT**

A power module includes a substrate, chips, supporting pillars, a metal plate and bonding bodies is disclosed. The substrate includes a metallic layer. The chips are on the metallic layer of the substrate, and each of the chips includes a source, a gate, and a drain. The supporting pillars are on the chips. The metal plate is on the supporting pillars and connected with the supporting pillars. The bonding bodies connect the metal plate and the metallic layer.

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